PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Sang Hyun YUN	10/24/2011
Cha-Dong KIM	10/24/2011
Jung-In PARK	10/24/2011
Hi Kuk LEE	10/24/2011
Su-Yeon SIM	10/24/2011

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13309679

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NAME OF SUBMITTER:	Hae-Chan Park

Total Attachments: 3
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ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

☒ an application for United States Letters Patent entitled **PHOTOSENSITIVE FILM PATTERN AND METHOD FOR MANUFACTURING A PHOTOSENSITIVE FILM PATTERN** ("Application");

☐ upon which United States Letters Patent, Patent Number ______________, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

Samsung Electronics Co., Ltd.
416 Maetan-dong, Yeongtong-gu
Gyeonggi-do
Suwon-si
Republic of Korea

Samsung Electronics Co., Ltd. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

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Fifth Inventor's Signature: Sim Su-yeon

Date: 2011. 10. 24